Place Your Title Here, in Bold, Using Initial-Capitals, 12 Point

Place author name(s) here, in 11 point type

Place your company name here

Place your company address here

Place your company city/country here

Email here

Abstract

This is the Template for SEMI-THERM authors who are preparing a full paper for the symposium. Place abstract here: usually a single paragraph summarizing the problem, approach, and results that are in the paper. Print out these instructions before pasting your paper’s text into this document, so you can refer back to the template. When your final draft manuscript is ready, you will distill it to a PDF, then upload it on our Submission Portal. Select “manuscript for peer review” for “Type of Submission” by the submittal date if you want your manuscript to be peer-reviewed. If you are submitting your paper as a result of an accepted Abstract, then simply upload your final manuscript for publication by the final due date.

Keywords

Keywords, separated, by commas

Nomenclature

Optional listing of terms and units

1. Discussion 1 Section Header, Self-numbering Format if Desired

Note that the use of numbered Section Headings is preferred for ease of referencing in the text, but is optional. To use the default numbering system, use Style: STH Section Heading 1 for the headings of all the sections numbered 1., 2., 3., etc. If you click on the heading for this section, you will see that it is STH Section Heading 1.

Each paper usually starts with a statement of the problem or situation, and the approach that is taken to resolve it. The second paragraph in the Section should start with a “line break", but do not add an extra blank line. The slight indent will clearly define the paragraphs.

*If a figure needs to be larger than one column, for proper viewing, you can format it like this, with text flowing around it. Choose “Format Picture / Layout” and select “Square”; then enlarge and position the figure. Place the caption below it.*

This first Section may also contain a summary of the past developments and background of what is already known, and published elsewhere. This is best summarized in your own paper, with references to other publications containing more-extensive discussions of this background information. [1] The references are placed at the end of the paper. [2]

Remember that you should not re-state long sections of material that are already readily available in the archival literature; simply summarize it, then add a reference or two. We suggest that you use references to peer-reviewed archival literature from past SEMI-THERMs, from the IEEE Transactions on Components, Packaging and Manufacturing Technology (T-CPMT: eps.ieee.org) or from the ASME J-EP; a good resource is the IEEE Xplore on-line system, which can be easily searched for keywords pertinent to your subject (see your university/company librarian for the password for downloading IEEE papers of interest off the internet).

1. Discussion 2 Section Header

Text about initial steps in your preparation and analysis. You should use the pre-formatted “styles” in the Word toolbar above: type the Section Header, then select “STH Section Header 1” (or “2” or “3”) style, above; your Header text will change to Bold and be left-justified, with spacing added above and below it. Then hit enter/return; this will automatically place you in the “STH Text” style/format for typing the text paragraphs for that Section. Or, type the text for the section, select all the paragraphs, and choose the “STH Text” style, above.

Perhaps you have already prepared your manuscript as a document in Word or in another Word Processor. You may then copy and paste existing headers and text into this Word template, then select the Title, Authors, Section Headers, and Text areas and Apply (“paint”) the appropriate Style, from the “STH” Styles provided. Look up the word “style” in the Word Help system for guidance.

1. Discussion 3 Section Header

Your figures, tables, and diagrams, if computer-generated, should be placed within this document, with text placed/flowed around them. These figures may have been created in a spreadsheet or graphics program; you should simplify them so that they are easily readable, and reduce them to fit into one column (or make them wider, if needed, with text from the second column flowing around them, as shown below). We prefer to have color figures and graphics, where appropriate; these will be viewable in color through the USB Drive or CD-ROM’s browser (Acrobat Reader).

Your text should flow completely to the foot of the page. On 8.5x11 sheets, the top of your title (and the top line on each succeeding page) should be 0.67” from the top (you may need to adjust slightly, to match the Format Specification sheet), and the columns should continue to within 0.67” of the bottom.

If you are using A4 paper, then you may need to adjust the borders in this template file. In “Page Setup”, select “paper size” of A4; then select “Margins” and set left and right to 13.8 mm, and top and bottom to 25.2 mm. The gutter between columns should already be about 5 mm; it can be set under Format/Columns.

* 1. Discussion 3.1 sub heading

Note: the paragraph style for second-level Section Heading is STH Section Heading 2. Type or copy text for the sub-section if needed. Lower levels of heading are also permitted.

|  |  |  |
| --- | --- | --- |
|  |  |  |
|  |  |  |
|  |  |  |
|  |  |  |
|  |  |  |
|  |  |  |

**Table X:** The Figure or Table caption is under the item, with the “Table X:” in bold and the text in “STH Text” Style. Don’t indent the paragraph. (It is also fine to put Table captions *above* the table, and Figure captions *below* the figure.)

* 1. Discussion 3.2 sub-heading

The footer on the first page of your paper will be filled by our staff with the copyright notification and the Symposium name. You should leave this area blank, as well as the footers on the other pages.

1. Conclusions

Place conclusions here.

Acknowledgments

Place acknowledgments here, if needed.

References

1. Downey, D. F. et al, Ion Implantation Technology, Prentice-Hall (New York, 2014), pp. 65-67. [A book reference …]

2. Aranyosi, A., M. R. Boyle, H. A. Buyse, "Compact Air-Cooled Heat Sinks for Power Packages", IEEE Trans on Components, Packaging & Mfg Technology Vol. 52, No. 4, pp. 442-451, 2019. [A reference to a journal article …]

3. Azar, K, R. S. McLeod, R. E. Caron, "Narrow Channel Heat Sink for Cooling of High Powered Electronic Components", Proc of 27th IEEE Semiconductor Thermal Measurement & Management Symp, pp. 12-19, 2018. [A reference to a presentation at a Conference…]